

Master Bond EP21AOLV-1 Two Part, Room Temperature Curing Epoxy System

Category: Polymer, Thermoset, Epoxy, Epoxy Encapsulant, Unreinforced

Material Notes:

Product Description: Master Bond Polymer Adhesive EP21AOLV-1 is a two component, thermally conductive, electrically isolating epoxy adhesive, sealant and coating. This versatile system will adhere to a wide variety of substrates including metals, glass, ceramics and many plastics. While its primary use is for potting and encapsulating, it is also an excellent adhesive that forms high strength bonds. EP21AOLV-1 resists a wide range of chemicals including water, oils, fuels and many solvents. The service temperature range for this epoxy is -60°F to +250°F. Other properties include a low coefficient of expansion, excellent dimensional stability, a high modulus and compressive strength. These physical properties combined with good thermal conductivity and electrical insulation make EP21AOLV-1 good for a variety of applications. When used as an encapsulating system, it has convenient handling with a one to one mix ratio by weight or volume. Its ability to flow readily and smoothly is another benefit. The color of Part A is gray; the color of Part B is off-white. EP21AOLV-1 is widely used in the electronic, electro-optical and related industries where excellent heat transfer and electrical insulation are required. Product Advantages: Convenient mixing: non-critical equal weight or volume ratio. Easy application: readily flowable when potting; brushable when bonding. Versatile cure schedules: ambient temperature cures or fast elevated temperature cures. High bonding strength to a wide variety of substrates. Low coefficient of expansion, low shrinkage and good dimensional stability. Great durability, thermal shock and chemical resistance. Thermal conductivity, over 10 BTU-in/ft2 *hr*°F. Excellent electrical insulation properties. Long working life. Information provided by MasterBond®

Order this product through the following link:

http://www.lookpolymers.com/polymer_Master-Bond-EP21AOLV-1-Two-Part-Room-Temperature-Curing-Epoxy-System.php

| Physical Properties | Metric | English | Comments |
|---------------------|------------------|------------------|----------|
| Viscosity | 4000 - 8000 cP | 4000 - 8000 cP | Part A |
| | 50000 - 65000 cP | 50000 - 65000 cP | Part B |

| Mechanical Properties | Metric | English | Comments | |
|---------------------------|----------------------|----------------------|-------------|--|
| Hardness, Shore D | >= 80 | >= 80 | | |
| Tensile Strength at Break | >= 34.5 MPa | >= 5000 psi | | |
| rensile Strength at Dreak | @Temperature 23.9 °C | @Temperature 75.0 °F | | |
| Tensile Modulus | >= 3.10 GPa | >= 450 ksi | | |
| Tensile Modulus | @Temperature 23.9 °C | @Temperature 75.0 °F | | |
| Compressive Strength | >= 96.5 MPa | >= 14000 psi | | |
| Shear Strength | >= 7.58 MPa | >= 1100 psi | Al/Al, bond | |

| Thermal Properties | Metric | English | Comments |
|--------------------|---------------------|-----------------------|----------|
| CTE, linear | 22.0 - 25.0 μm/m-°C | 12.2 - 13.9 μin/in-°F | |
| | | | |



| Thermal Properties 19 | Metric ^{4 W/m-K} | English | Comments |
|----------------------------------|---------------------------|----------|----------|
| Maximum Service Temperature, Air | 121 °C | 250 °F | |
| Minimum Service Temperature, Air | -51.1 °C | -60.0 °F | |

| Electrical Properties | Metric | English | Comments |
|-----------------------|--|--|----------|
| Volume Resistivity | >= 1.00e+13 ohm-cm | >= 1.00e+13 ohm-cm | |
| Dielectric Constant | 4.62 | 4.62 | |
| @Temperature 25 | | @Temperature 77.0 °F | |
| Dielectric Strength | >= 15.7 kV/mm | >= 400 kV/in | |
| Dielectric Strengtri | @Thickness 3.17 mm | @Thickness 0.125 in | |
| | 0.0080 | 0.0080 | |
| Dissipation Factor | @Frequency 60.0 Hz, Temperature 25.0 °C | @Frequency 60.0 Hz, Temperature 77.0 °F | |

| Processing Properties | Metric | English | Comments | |
|-----------------------|----------------------|----------------------|----------------------------------|--|
| Cure Time | 120 - 180 min | 2.00 - 3.00 hour | | |
| | @Temperature 93.3 °C | @Temperature 200 °F | | |
| | 2880 - 4320 min | 48.0 - 72.0 hour | | |
| | @Temperature 23.9 °C | @Temperature 75.0 °F | | |
| Pot Life | 90 - 120 min | 90 - 120 min | 100 gram mass | |
| Shelf Life | 6.00 Month | 6.00 Month | in original, unopened containers | |
| | @Temperature 23.9 °C | @Temperature 75.0 °F | in original, unopened containers | |

| Descriptive Properties | Value | Comments |
|------------------------|-------|---------------------|
| Mixing Ratio (A to B) | 1:1 | by weight or volume |

Contact Songhan Plastic Technology Co.,Ltd.

Website: www.lookpolymers.com Email: sales@lookpolymers.com

Tel: +86 021-51131842 Mobile: +86 13061808058 Skype: lookpolymers

Address: United North Road 215, Fengxian District, Shanghai City, China